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Reduction of exhalation of formaldehyde from chipboards - by spraying hot boards before stacking with ammonia yielding materials
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DE 2829021	B	19800103				198002	B
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Abstract (Basic): DE 2829021 B

The surface of hot chip or fibre board plates bonded by aminoaldehyde resins, is treated with urea or some other material capable of spliting off ammonia, to reduce the amt. of formaldehyde given off. The materials are applied to the plates immediately or shortly after they are removed from the hot press.

Watery solutions of the urea or other materials are used.

An aq. soln. of 5 to 20% urea may be used and be sprayed on the plates at 10 to 100g solid matter per m2 plate surface, at plate thicknesses from 5 to 50mm. The sprayed plates are stacked whilst hot.

Treatment reduces HCHO evolution without reducing the tensile strength of the boards. At the same time, the surfaces of the boards are left so that they can be coated with pigments or fabrics or laminating papers without difficulty.